



3.0 mmx1.0 mm RIGHT ANGLE SMD CHIP LED LAMP

Features

- 3.0mm x 1.0mm right angle SMT LED, 2.5mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for back light and indicator.
- Various colors and lens types available.
- $\bullet Package: 2000pcs \, / \, reel.$
- •Moisture sensitivity level : level 3.
- •RoHS compliant.





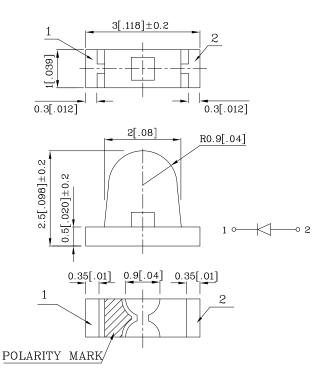


ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.15(0.006")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (TA=25°C)	DG (InGaN)	Unit			
Reverse Voltage	VR	5	V		
Forward Current	IF	25	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	150	mA		
Power Dissipation	PD	102.5	mW		
Operating Temperature	TA	-40 ~ +85	0.0		
Storage Temperature	Tstg	-40 ~ +85	°C		



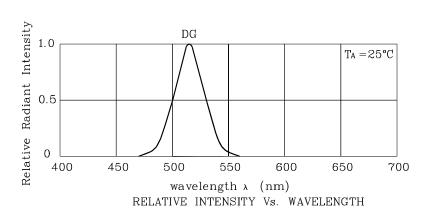
Operating Characteristic (Ta=25°C)	DG (InGaN)	Unit	
Forward Voltage (Typ.) (IF=20mA)	VF	3.3	V
Forward Voltage (Max.) (IF=20mA)	VF	4.1	V
Reverse Current (Max.) (V _R =5V)	IR	50	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λΡ	515	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λ D	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	Δλ	30	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	С	45	pF

_	Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2 0 1/2
					min.	typ.		
-	XZDG56W-1	Green	InGaN	Water Clear	500	795	515	30°
	Published Date: SEP 01,2010		Drawing No :XDSB5173		V1	Chec	ked : B.L.LIU	P.1/4

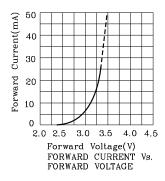
Part Number: XZDG56W-1

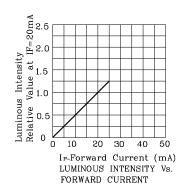
3.0 mmx1.0 mm RIGHT ANGLE SMD CHIP LED LAMP

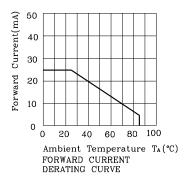


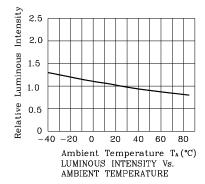


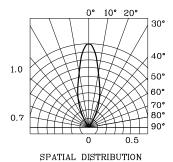
♦ DG







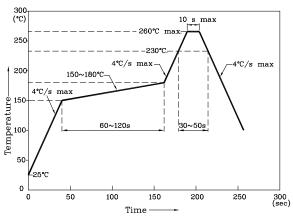




3.0 mmx1.0 mm RIGHT ANGLE SMD CHIP LED LAMP

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

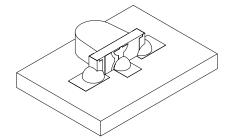
Reflow Soldering Profile For Lead-free SMT Process.



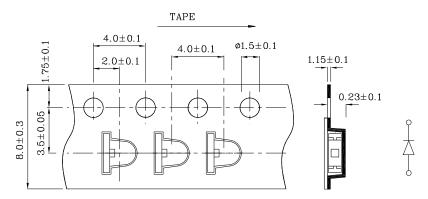
- NOTES:
 - 1. Maximum soldering temperature should not exceed 260°c.
 - 2. Recommended reflow temperature: 145°c-260°c.
 - 3. Do not put stress to the epoxy resin during high temperatures conditions.
- ❖ Recommended Soldering Pattern (Units: mm; Tolerance: ±0.1)
 - 5 2 1.5 0.9

೧

❖ The device has a single mounting surface. The device must be mounted according to the specifications.



* Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

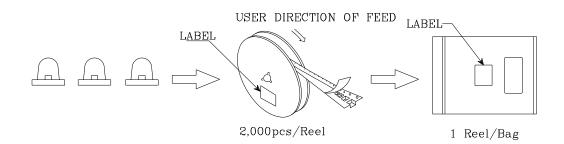


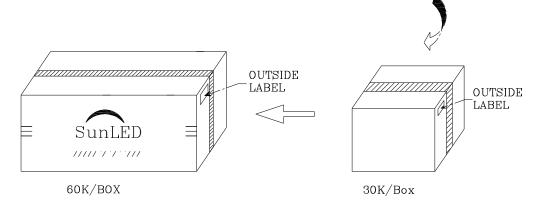
Part Number: XZDG56W-1

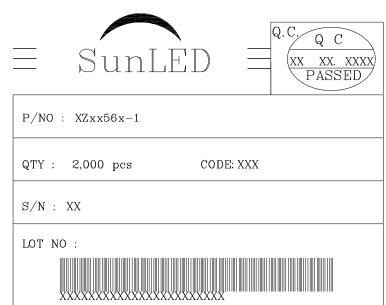
3.0~mmx1.0~mm RIGHT ANGLE SMD CHIP LED LAMP

PACKING & LABEL SPECIFICATIONS

XZDG56W-1







Published Date: SEP 01,2010 Drawing No: XDSB5173 V1 Checked: B.L.LIU P.4/4

RoHS Compliant